

METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES HAVING AN ENCAPSULATED INSULATION LAYER

Abstract of the Disclosure

An integrated circuit device is manufactured by forming an insulating layer on a substrate. A capping layer is formed on the insulating layer and both the capping layer and the insulating layer are patterned. Insulating spacers are formed on sidewalls of the insulating layer so that the insulating spacers, the capping layer, and the substrate enclose the insulating layer.

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